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October 2010

74AUP1G58 TinyLogic[®] Low Power Universal Configurable Two-Input Logic Gate

Features

- 0.8V to 3.6V V_{CC} Supply Operation
- 3.6V Over-Voltage Tolerant I/Os at V_{CC} from 0.8V to 3.6V
- High Speed tpd
 - 3.1ns: Typical at 3.3V
- Power-Off High-Impedance Inputs and Outputs
- Low Static Power Consumption
 - I_{CC}=0.9µA Maximum
- Low Dynamic Power Consumption
 - C_{PD}=2.9pF Typical at 3.3V
- Ultra-Small MicroPak™ Packages

Description

The 74AUP1G58 is a universal configurable 2-input logic gate that provides a high performance and low power solution ideal for battery-powered portable applications. This product is designed for a wide low voltage operating range (0.8V to 3.6V) and guarantees very low static and dynamic power consumption across the entire voltage range. All inputs are implemented with hysteresis to allow for slower transition input signals and better switching noise immunity.

The 74AUP1G58 provides for multiple functions as determined by various configurations of the three inputs. The potential logic functions provided are AND, OR, NOR, NAND, and XNOR, inverter and non-inverter. Refer to Figures 2 to 8.

Ordering Information

Part Number	Top Mark	Package	Packing Method
74AUP1G58L6X	AC	6-Lead MicroPak™, 1.0mm Wide	5000 Units on Tape & Reel
74AUP1G58FHX	AC	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

Pin Configurations

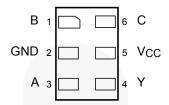


Figure 1. MicroPak™ (Top Through View)

Pin Definitions

Pin #	Name	Description
1	В	Data Input
2	GND	Ground
3	Α	Data Input
4	Y	Output
5	V _{CC}	Supply Voltage
6	С	Data Input

Function Table

Inputs			74AUP1G58
С	В	Α	Y=Output
L	L	L	L
L	L	Н	Н
L	Н	L	L
L	Н	Н	Н
Н	L	L	Н
Н	L	Н	Н
Н	Н	L	L
Н	Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

Function Selection Table

2-Input Logic Function	Connection Configuration		
2-Input AND with Inverted Input	Figure 3, Figure 4		
2-Input NAND	Figure 2		
2-Input NAND with Both Inputs Inverted	Figure 5		
2-Input OR	Figure 5		
2-Input OR with Both Inputs Inverted	Figure 2		
2-Input NOR with Inverted Inputs	Figure 3, Figure 4		
2-Input XOR	Figure 6		
Inverter	Figure 7		
Buffer	Figure 8		

74AUP1G58 Logic Configurations

Figure 2 through Figure 8 show the logical functions that can be implemented using the 74AUP1G58. The diagrams show the DeMorgan's equivalent logic duals for a given two-input function. The logical

implementation is next to the board-level physical implementation of how the pins of the function should be connected.

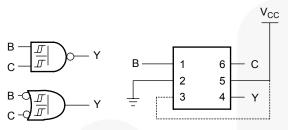


Figure 2. 2-Input NAND Gate or 2-Input OR with Both Inputs Inverted

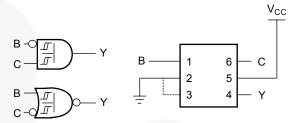


Figure 3. 2-Input AND with Inverted B Input or 2-Input NOR Gate with Inverted C Input

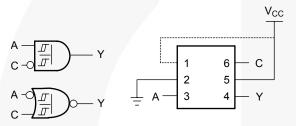


Figure 4. 2-Input AND with Inverted C Input or 2-Input NOR Gate with Inverted A Input

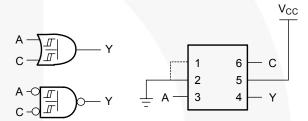


Figure 5. 2-Input OR Gate or 2-Input NAND Gate with Both Inputs Inverted

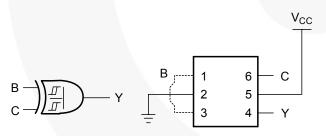


Figure 6. 2-Input XOR Gate

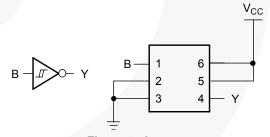


Figure 7. Inverter

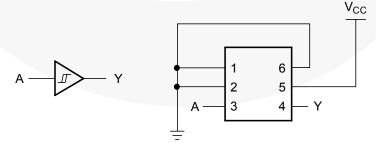


Figure 8. Buffer

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	meter	Min.	Max.	Unit
V _{CC}	Supply Voltage		-0.5	4.6	V
V _{IN}	DC Input Voltage		-0.5	4.6	V
\/	DC Output Voltage	HIGH or LOW State ⁽¹⁾	-0.5	V _{CC} + 0.5	V
V _{OUT}	DC Output Voltage	V _{CC} =0V	-0.5	4.6	V
I _{IK}	DC Input Diode Current	V _{IN} < 0V		-50	mA
1	DC Outrout Diada Current	V _{OUT} < 0V		-50	A
I _{OK}	DC Output Diode Current	V _{OUT} > V _{CC}		+50	mA
I _{OH} / I _{OL}	DC Output Source / Sink Curre	nt		±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per	Supply Pin		±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bi	as		+150	°C
T_L	Junction Lead Temperature, Sc	oldering 10s		+260	°C
P_{D}	Dower Discipation at 195°C	MicroPak-6		130	mW
FD	Power Dissipation at +85°C	MicroPak2-6		120	IIIVV
ESD	Human Body Model, JEDEC:JE	SD22-A114		5000+	V
ESD	Charged Device Model, JEDEC	:JESD22-C101		2000	V

Note:

Recommended Operating Conditions⁽²⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit	
Vcc	Supply Voltage		0.8	3.6	V	
V_{IN}	Input Voltage		0	3.6	V	
V	Output Voltage	V _{CC} =0V	0	3.6	V	
V_{OUT}	Output Voltage	HIGH or LOW State	0	Vcc	7 v	
		V _{CC} =3.0V to 3.6V		±4.0		
	H/I _{OL} Output Current	V _{CC} =2.3V to 2.7V		±3.1		
1 /1		V _{CC} =1.65V to 1.95V		±1.9	mA	
IOH/IOL		V _{CC} =1.4V to 1.6V		±1.7		
		V _{CC} =1.1V to 1.3V		±1.1	\supset \cap	
		V _{CC} =0.8V		±20.0	μA	
T _A	Operating Temperature, Free Air		-40	+85	°C	
0	Thermal Desigtance	MicroPak-6		500	°CAM	
$ heta_{\sf JA}$	Thermal Resistance	MicroPak2-6		560	°C/W	

Note:

2. Unused inputs must be held HIGH or LOW. They may not float.

^{1.} I_O absolute maximum rating must be observed.

DC Electrical Characteristics

Cumb a l	Donorastan	v	Conditions	T _A =+	25°C	T _A =-40 to +85°C		Units	
Symbol	Parameter	V _{cc}	Conditions	Min.	Max.	Min.	Max.	Unit	
		0.80		0.30	0.60	0.30	0.60		
		1.10		0.53	0.90	0.53	0.90		
V_P	Positive Threshold	1.40		0.74	1.11	0.74	1.11	V	
V P	Voltage	1.65		0.91	1.29	0.91	1.29	V	
		2.30		1.37	1.77	1.37	1.77		
		3.00		1.88	2.29	1.88	2.29		
		0.80		0.10	0.60	0.10	0.60		
		1.10		0.26	0.65	0.26	0.65		
V_N	Negative	1.40		0.39	0.75	0.39	0.75	V	
۷N	Threshold Voltage	1.65		0.47	0.84	0.47	0.84	ľ	
		2.30		0.69	1.04	0.69	1.04		
		3.00		0.88	1.24	0.88	1.24		
		0.80		0.07	0.50	0.07	0.50		
		1.10		0.08	0.46	0.08	0.46		
V	Hysteresis Voltage	1.40		0.18	0.56	0.18	0.56	V	
V_H	Hysteresis voitage	1.65		0.27	0.66	0.27	0.66	ľ	
		2.30		0.53	0.92	0.53	0.92		
		3.00		0.79	1.31	0.79	1.31		
		$0.80 \leq V_{CC} \leq 3.60$	I _{OH} =-20μA	V _{CC} -0.1		V _{CC} -0.1			
		1.10 ≤ V _{CC} ≤ 1.30	I _{OH} =-1.1mA	0.75 x V _{CC}		0.70 x V _{CC}			
		1.40 ≤ V _{CC} ≤ 1.60	I _{OH} =-1.7mA	1.11		1.03			
	HIGH Level Output	1.65 ≤ V _{C,C} ≤ 1.95	I _{OH} =-1.9mA	1.32		1.30			
V_{OH}	Voltage		I _{OH} =-2.3mA	2.05		1.97		V	
			$2.30 \leq V_{CC} \leq 2.70$	I _{OH} =-3.1mA	1.90		1.85		
			I _{OH} =-2.7mA	2.72		2.67			
			$3.00 \le V_{CC} \le 3.60$	I _{OH} =-4.0mA	2.60		2.55		
		$0.80 \leq V_{CC} \leq 3.60$	I _{OL} =20μA		0.10	/	0.10		
		1.10 ≤ V _{CC} ≤ 1.30	I _{OL} =1.1mA		0.30 x V _{CC}	/	0.30 x V _{CC}		
		1.40 ≤ V _{CC} ≤ 1.60	I _{OL} =1.7mA		0.31		0.37		
	LOW Level Output		I _{OL} =1.9mA		0.31		0.35		
V _{OL}	Voltage		I _{OL} =2.3mA		0.31		0.33	V	
	Y	$2.30 \leq V_{CC} \leq 2.70$	I _{OL} =3.1mA		0.44		0.45		
			I _{OL} =2.7mA		0.31		0.33		
		$2.70 \leq V_{CC} \leq 3.60$	I _{OL} =4.0mA		0.44		0.45		
I _{IN}	Input Leakage Current	0V to 3.6V	$0 \leq V_{IN} \leq 3.6$		±0.1		±0.5	μA	
I _{OFF}	Power Off Leakage Current	0V	$0 \leq (V_{IN}, V_O) \leq 3.6$		0.2		0.6	μA	
Δl_{OFF}	Additional Power Off Leakage Current	0V to 0.2V	V _{IN} or V _O = 0V to 3.6V		0.2		0.6	μA	
I _{CC}	Quiescent Supply Current	0.8V to 3.6V	V _{IN} - V _{CC} or GND		0.5		0.9	μA	
	Current		$V_{CC} \leq V_{IN} \leq 3.6$				±0.9		
ΔI_{CC}	Increase in I _{CC} per Input	3.3V	V _{IN} = V _{CC} -0.6V		40.0		50.0	μA	

AC Electrical Characteristics

Symbol Parameter		V _{cc}	Conditions		T _A =+25°C		T _A =-40 to +85°C		Units	Figure
•				Min.	Тур.	Max	Min	Max		J
		0.80			22.8					
		$1.10 \le V_{CC} \le 1.30$		2.8	8.9	12.9	2.6	13.1		
		$1.40 \le V_{CC} \le 1.60$	0.550.440	2.4	5.2	7.9	2.4	8.6		
		$1.65 \le V_{CC} \le 1.95$	$C_L=5pF, R_L=1M\Omega$	2.0	4.4	6.5	2.0	7.2		
		$2.30 \leq V_{CC} \leq 2.70$		1.7	3.6	4.9	1.8	5.2		
		$3.00 \leq V_{CC} \leq 3.60$		1.3	3.1	4.2	1.6	4.7		
		0.80			26.4					
		$1.10 \le V_{CC} \le 1.30$		3.2	7.4	14.5	3.0	14.9		
		$1.40 \leq V_{CC} \leq 1.60$	C _L =10pF,	2.7	5.4	8.7	2.7	9.4		
		$1.65 \le V_{CC} \le 1.95$	$R_L=1M\Omega$	2.3	4.5	7.1	2.3	7.9		
		$2.30 \leq V_{CC} \leq 2.70$		1.9	3.8	5.3	1.9	5.9		
t t	Propagation	$3.00 \leq V_{CC} \leq 3.60$		1.3	3.5	4.6	1.3	4.9	ns	Figure 9
t _{PHL} , t _{PLH}	Delay	0.80			29.9				115	Figure 10
		$1.10 \le V_{CC} \le 1.30$		3.6	9.9	16.1	3.3	16.7		
		$1.40 \le V_{CC} \le 1.60$	C _L =15pF,	3.0	6.5	9.7	3.0	10.5		
		$1.65 \le V_{CC} \le 1.95$	$R_L=1M\Omega$	2.8	5.2	7.9	2.5	8.7		
		$2.30 \leq V_{CC} \leq 2.70$		2.3	4.1	5.9	2.3	6.6		
		$3.00 \leq V_{CC} \leq 3.60$		1.3	3.5	5.2	1.3	5.5		
		0.80			28.8		31.4			
		$1.10 \le V_{CC} \le 1.30$		3.4	9.1	18.5	3.4	19.0		
		$1.40 \le V_{CC} \le 1.60$	C _L =30pF,	3.1	5.5	10.5	3.1	11.0		
		$1.65 \le V_{CC} \le 1.95$	$R_L=1M\Omega$	2.1	4.4	8.7	2.1	9.5		
		$2.30 \leq V_{CC} \leq 2.70$		1.7	3.6	6.5	1.7	7.1		
		$3.00 \leq V_{CC} \leq 3.60$		1.3	3.1	5.6	1.3	6.3		
C _{IN}	Input Capacitance	0			0.8				pF	
C_OUT	Output Capacitance	0			1.7				pF	
	0.80			1.8						
		$1.10 \le V_{CC} \le 1.30$			1.82				pF	
C.	Power	$1.40 \le V_{CC} \le 1.60$	V _{IN} =0V or V _{CC} ,		1.85					
C_{PD}	Dissipation Capacitance	$1.65 \le V_{CC} \le 1.95$	f=10MHz		1.9					
		$2.30 \leq V_{CC} \leq 2.70$			2.1					
		$3.00 \leq V_{CC} \leq 3.60$			2.9					

AC Loadings and Waveforms

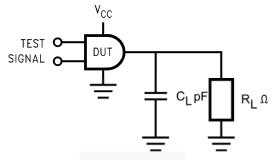


Figure 9. AC Test Circuit

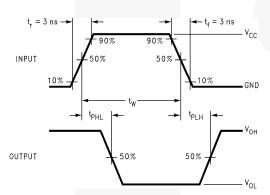
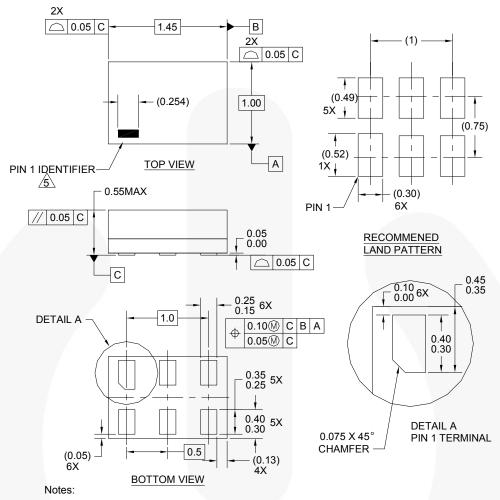


Figure 10. AC Waveforms

Symbol		V _{cc}				
Symbol	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V	1.5V ± 0.10V	1.2V ± 0.10V	V8.0
V _{mi}	V _{CC} /2					
V_{mo}	V _{CC} /2					

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5 PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

Figure 11. 6-Lead, MicroPak™, 1.0mm Wide

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Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/logic/pdf/micropak-tr.pdf.

Package Designator	Tape Section	e Section Cavity Number		Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

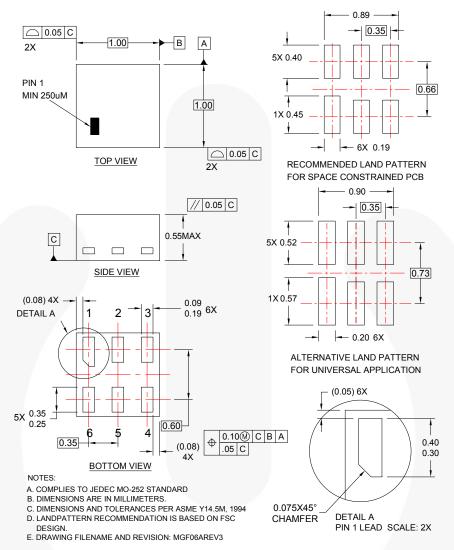


Figure 12. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch

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Package Designator	Tape Section	Tape Section Cavity Number C		Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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SuperFET®
SuperSOT™.3
SuperSOT™.8
SuperSOT™.8
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SyncFET™
Sync-Lock™

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The Power Franchise®

P wer franchise TinyBoost™ TinyBuck™

TinyCalc™
TinyCalc™
TinyCalc™
TinyPover™
TinyPover™
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UniFET™
VCX™
VisualMax™
XS™

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Rev. 150

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